Lattice Semiconductor Corporation - LFXP15C-4FN388I Datasheet

Welcome to E-XFL.COM

Understanding Embedded - FPGAs (Field Programmable Gate Array)

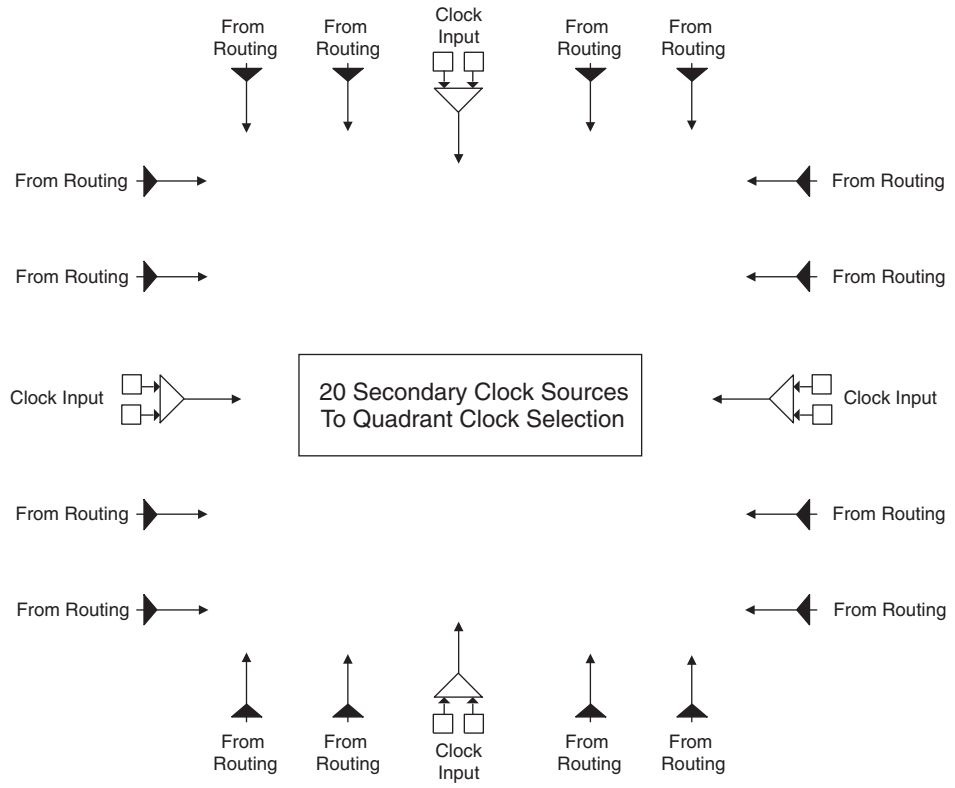
Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	15000
Total RAM Bits	331776
Number of I/O	268
Number of Gates	-
Voltage - Supply	1.71V ~ 3.465V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	388-BBGA
Supplier Device Package	388-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfxp15c-4fn388i

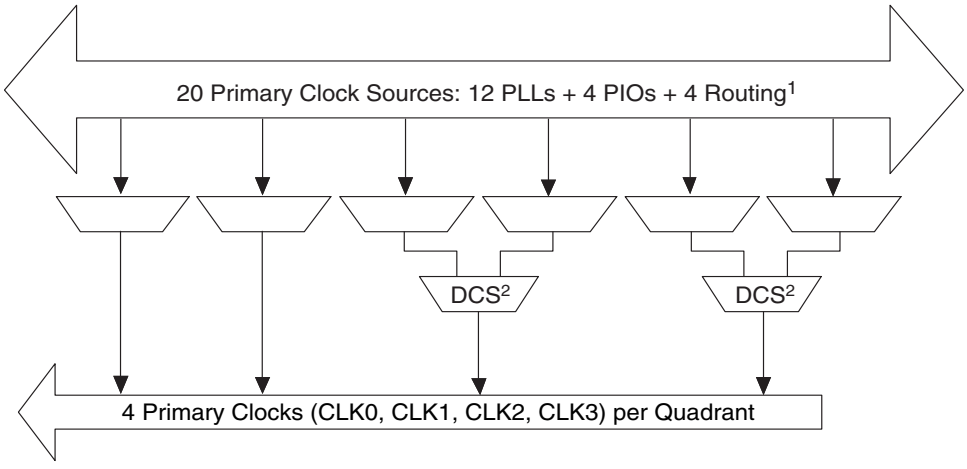
Figure 2-6. Secondary Clock Sources



Clock Routing

The clock routing structure in LatticeXP devices consists of four Primary Clock lines and a Secondary Clock network per quadrant. The primary clocks are generated from MUXs located in each quadrant. Figure 2-7 shows this clock routing. The four secondary clocks are generated from MUXs located in each quadrant as shown in Figure 2-8. Each slice derives its clock from the primary clock lines, secondary clock lines and routing as shown in Figure 2-9.

Figure 2-7. Per Quadrant Primary Clock Selection



1. Smaller devices have fewer PLL related lines.
2. Dynamic clock select.

For more information on the PLL, please see details of additional technical documentation at the end of this data sheet.

Dynamic Clock Select (DCS)

The DCS is a global clock buffer with smart multiplexer functions. It takes two independent input clock sources and outputs a clock signal without any glitches or runt pulses. This is achieved irrespective of where the select signal is toggled. There are eight DCS blocks per device, located in pairs at the center of each side. Figure 2-12 illustrates the DCS Block Macro.

Figure 2-12. DCS Block Primitive

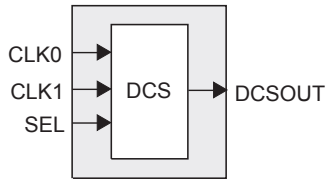
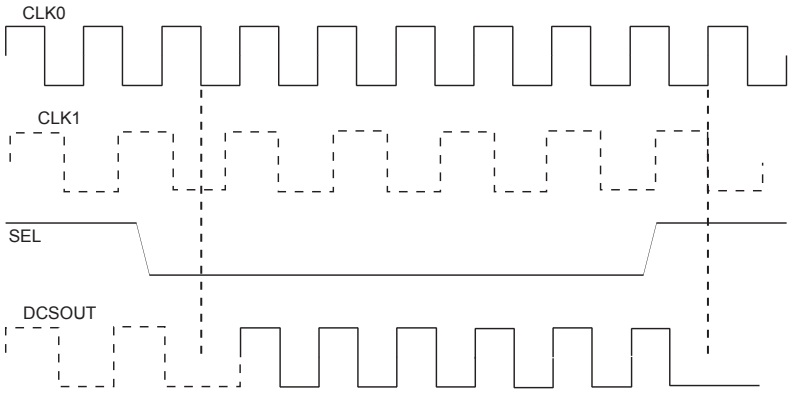


Figure 2-13 shows timing waveforms of the default DCS operating mode. The DCS block can be programmed to other modes. For more information on the DCS, please see details of additional technical documentation at the end of this data sheet.

Figure 2-13. DCS Waveforms



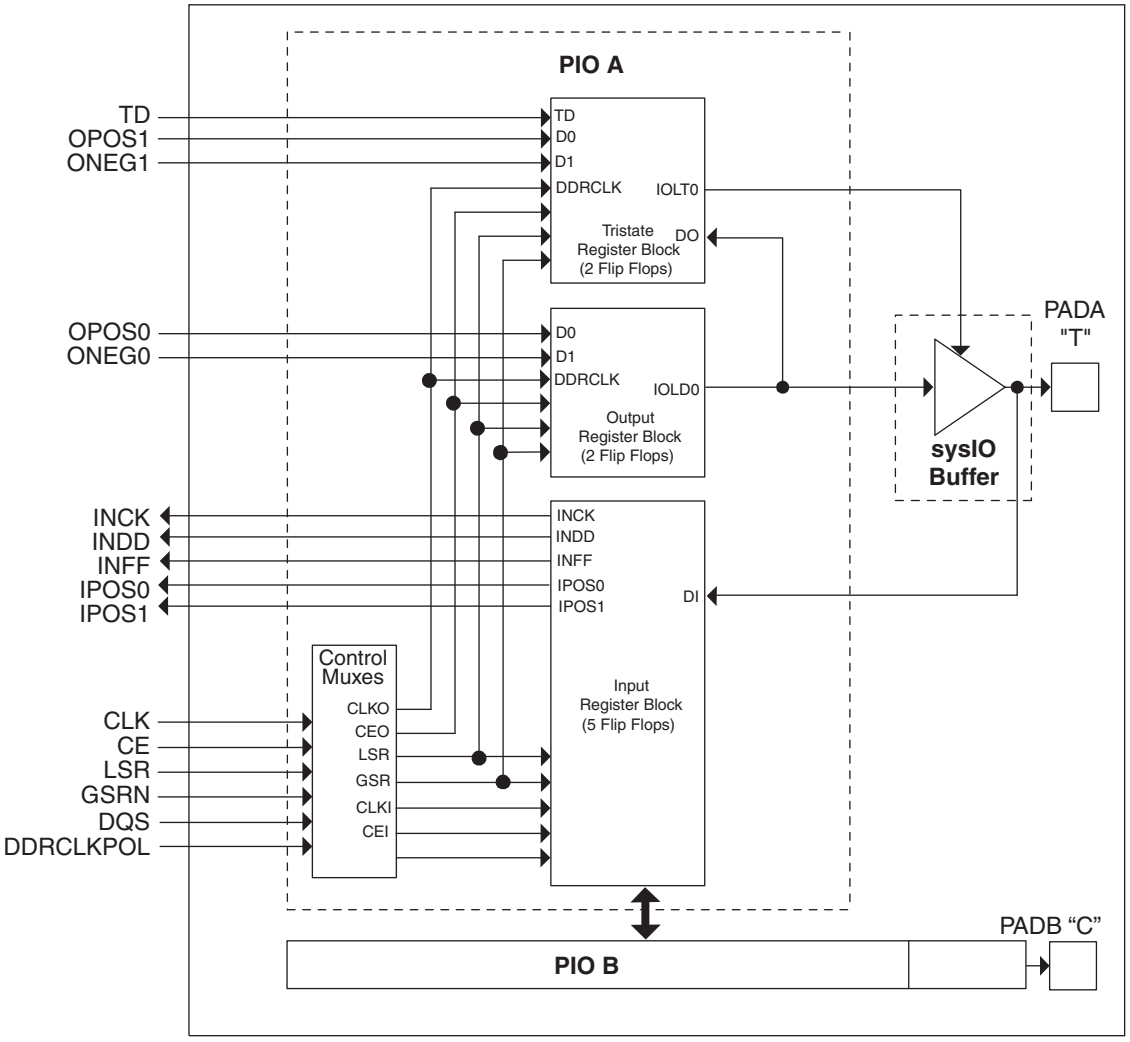
sysMEM Memory

The LatticeXP family of devices contain a number of sysMEM Embedded Block RAM (EBR). The EBR consists of a 9-Kbit RAM, with dedicated input and output registers.

sysMEM Memory Block

The sysMEM block can implement single port, dual port or pseudo dual port memories. Each block can be used in a variety of depths and widths as shown in Table 2-6.

Figure 2-17. PIC Diagram



In the LatticeXP family, seven PIOs or four (3.5) PICs are grouped together to provide two LVDS differential pairs, one PIC pair and one single I/O, as shown in Figure 2-18.

Two adjacent PIOs can be joined to provide a differential I/O pair (labeled as “T” and “C”). The PAD Labels “T” and “C” distinguish the two PIOs. Only the PIO pairs on the left and right edges of the device can be configured as LVDS transmit/receive pairs.

One of every 14 PIOs (a group of 8 PICs) contains a delay element to facilitate the generation of DQS signals as shown in Figure 2-19. The DQS signal feeds the DQS bus which spans the set of 13 PIOs (8 PICs). The DQS signal from the bus is used to strobe the DDR data from the memory into input register blocks. This interface is designed for memories that support one DQS strobe per eight bits of data.

The exact DQS pins are shown in a dual function in the Logic Signal Connections table in this data sheet. Additional detail is provided in the Signal Descriptions table in this data sheet.

Figure 2-21. Input Register DDR Waveforms

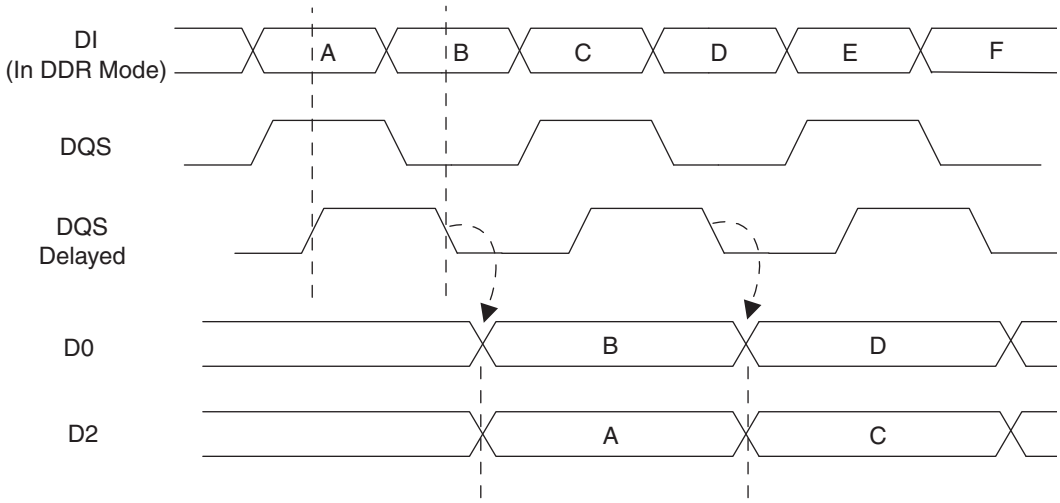
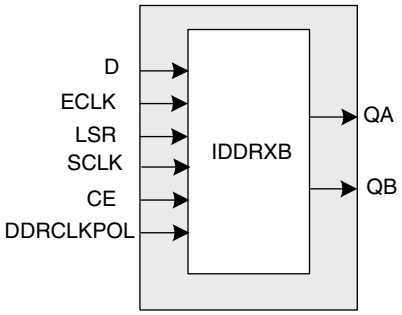


Figure 2-22. INDDRXB Primitive



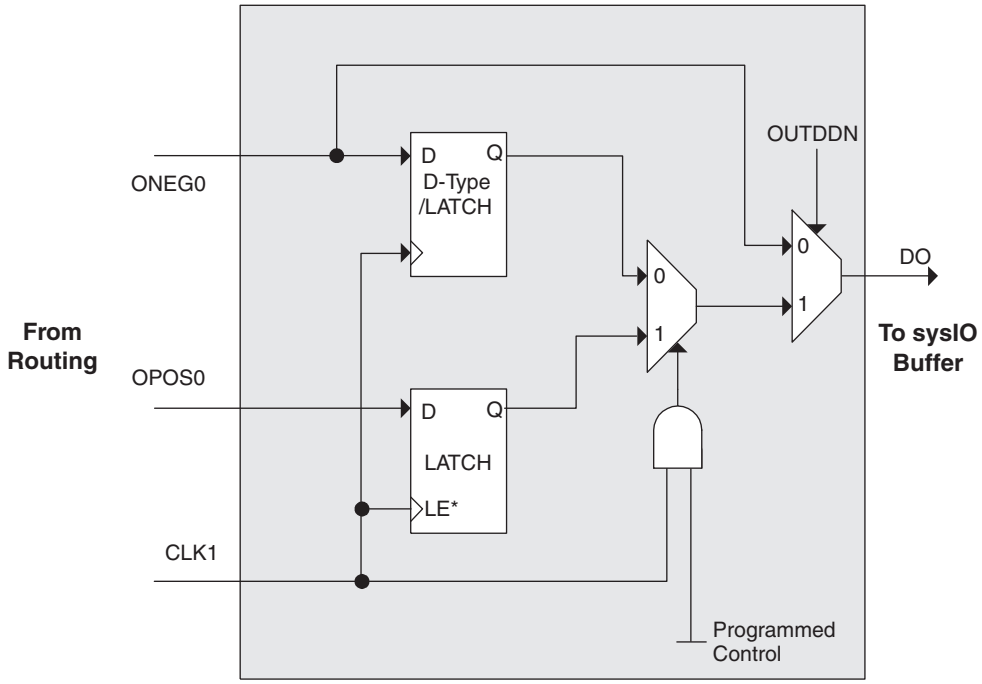
Output Register Block

The output register block provides the ability to register signals from the core of the device before they are passed to the sysIO buffers. The block contains a register for SDR operation that is combined with an additional latch for DDR operation. Figure 2-23 shows the diagram of the Output Register Block.

In SDR mode, ONEG0 feeds one of the flip-flops that then feeds the output. The flip-flop can be configured as a D-type or as a latch. In DDR mode, ONEG0 is fed into one register on the positive edge of the clock and OPOS0 is latched. A multiplexer running off the same clock selects the correct register for feeding to the output (D0).

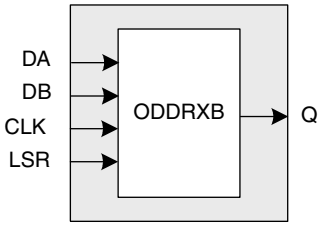
Figure 2-24 shows the design tool DDR primitives. The SDR output register has reset and clock enable available. The additional register for DDR operation does not have reset or clock enable available.

Figure 2-23. Output Register Block



*Latch is transparent when input is low.

Figure 2-24. ODDRXB Primitive



Tristate Register Block

The tristate register block provides the ability to register tri-state control signals from the core of the device before they are passed to the sysIO buffers. The block contains a register for SDR operation and an additional latch for DDR operation. Figure 2-25 shows the diagram of the Tristate Register Block.

In SDR mode, ONEG1 feeds one of the flip-flops that then feeds the output. The flip-flop can be configured a D-type or latch. In DDR mode, ONEG1 is fed into one register on the positive edge of the clock and OPOS1 is latched. A multiplexer running off the same clock selects the correct register for feeding to the output (D0).

Polarity Control Logic

In a typical DDR Memory interface design, the phase relation between the incoming delayed DQS strobe and the internal system Clock (during the READ cycle) is unknown.

The LatticeXP family contains dedicated circuits to transfer data between these domains. To prevent setup and hold violations at the domain transfer between DQS (delayed) and the system Clock a clock polarity selector is used. This changes the edge on which the data is registered in the synchronizing registers in the input register block. This requires evaluation at the start of the each READ cycle for the correct clock polarity.

Prior to the READ operation in DDR memories DQS is in tristate (pulled by termination). The DDR memory device drives DQS low at the start of the preamble state. A dedicated circuit detects this transition. This signal is used to control the polarity of the clock to the synchronizing registers.

sysIO Buffer

Each I/O is associated with a flexible buffer referred to as a sysIO buffer. These buffers are arranged around the periphery of the device in eight groups referred to as Banks. The sysIO buffers allow users to implement the wide variety of standards that are found in today's systems including LVCMOS, SSTL, HSTL, LVDS and LVPECL.

sysIO Buffer Banks

LatticeXP devices have eight sysIO buffer banks; each is capable of supporting multiple I/O standards. Each sysIO bank has its own I/O supply voltage (V_{CCIO}), and two voltage references V_{REF1} and V_{REF2} resources allowing each bank to be completely independent from each other. Figure 2-28 shows the eight banks and their associated supplies.

In the LatticeXP devices, single-ended output buffers and ratioed input buffers (LVTTL, LVCMOS, PCI and PCI-X) are powered using V_{CCIO}. LVTTL, LVCMOS33, LVCMOS25 and LVCMOS12 can also be set as a fixed threshold input independent of $V_{CCIO.}$ In addition to the bank V_{CCIO} supplies, the LatticeXP devices have a V_{CC} core logic power supply, and a V_{CCAUX} supply that power all differential and referenced buffers.

Each bank can support up to two separate VREF voltages, VREF1 and VREF2 that set the threshold for the referenced input buffers. In the LatticeXP devices, a dedicated pin in a bank can be configured to be a reference voltage supply pin. Each I/O is individually configurable based on the bank's supply and reference voltages.

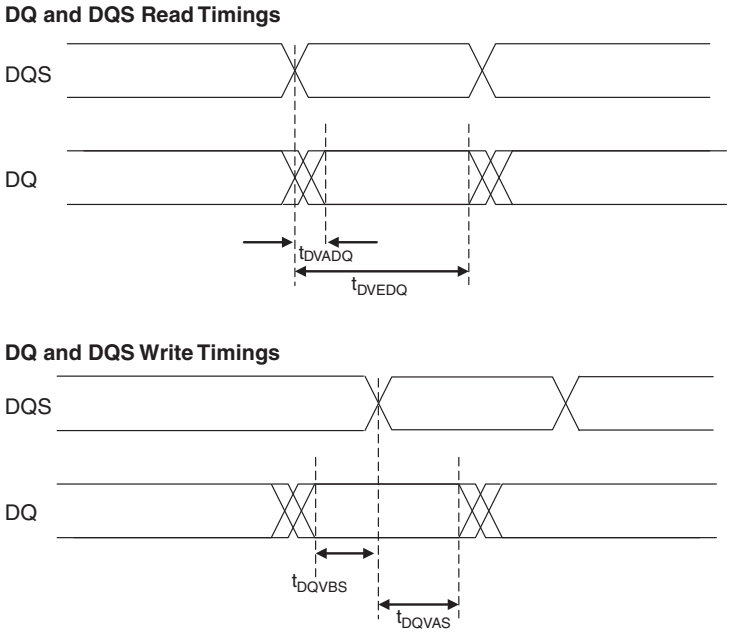
sysIO Differential Electrical Characteristics

LVDS

Over Recommended Operating Conditions

Parameter Symbol	Parameter Description	Test Conditions	Min.	Typ.	Max.	Units
V_{INP}, V_{INM}	Input Voltage		0	—	2.4	V
V_{THD}	Differential Input Threshold		+/-100	—	—	mV
V_{CM}	Input Common Mode Voltage	100mV ≤ V_{THD}	V_{THD}/2	1.2	1.8	V
		200mV ≤ V_{THD}	V_{THD}/2	1.2	1.9	V
		350mV ≤ V_{THD}	V_{THD}/2	1.2	2.0	V
I_{IN}	Input current	Power on or power off	—	—	+/-10	µA
V_{OH}	Output high voltage for V_{OP} or V_{OM}	R_T = 100 ohms	—	1.38	1.60	V
V_{OL}	Output low voltage for V_{OP} or V_{OM}	R_T = 100 ohms	0.9V	1.03	—	V
V_{OD}	Output voltage differential	(V_{OP} - V_{OM}), R_T = 100 ohms	250	350	450	mV
ΔV_{OD}	Change in V_{OD} between high and low		—	—	50	mV
V_{OS}	Output voltage offset	(V_{OP} - V_{OM})/2, R_T = 100 ohms	1.125	1.25	1.375	V
ΔV_{OS}	Change in V_{OS} between H and L		—	—	50	mV
I_{OSD}	Output short circuit current	V_{OD} = 0V Driver outputs shorted	—	—	6	mA

Figure 3-5. DDR Timings



LatticeXP Internal Timing Parameters[1] (Continued)

Over Recommended Operating Conditions

Parameter	Description	-5		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t_{RSTO_EBR}	Reset To Output Delay Time from EBR Output Register	—	1.61	—	1.94	—	2.32	ns
PLL Parameters								
t_{RSTREC}	Reset Recovery to Rising Clock	1.00	—	1.00	—	1.00	—	ns
t_{RSTSU}	Reset Signal Setup Time	1.00	—	1.00	—	1.00	—	ns

1. Internal parameters are characterized but not tested on every device.

Timing v.F0.11

sysCLOCK PLL Timing

Over Recommended Operating Conditions

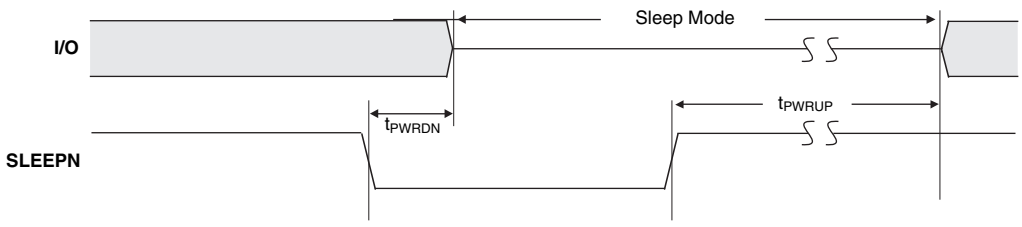
Parameter	Descriptions	Conditions	Min.	Typ.	Max.	Units
f_{IN}	Input Clock Frequency (CLKI, CLKFB)		25	—	375	MHz
f_{OUT}	Output Clock Frequency (CLKOP, CLKOS)		25	—	375	MHz
f_{OUT2}	K-Divider Output Frequency (CLKOK)		0.195	—	187.5	MHz
f_{VCO}	PLL VCO Frequency		375	—	750	MHz
f_{PFD}	Phase Detector Input Frequency		25	—	—	MHz
AC Characteristics						
t_{DT}	Output Clock Duty Cycle	Default duty cycle elected[3]	45	50	55	%
t_{PH}[4]	Output Phase Accuracy		—	—	0.05	UI
t_{OPJIT}[1]	Output Clock Period Jitter	f_{OUT} Š 100MHz	—	—	+/- 125	ps
		f_{OUT} < 100MHz	—	—	0.02	UIPP
t_{SK}	Input Clock to Output Clock Skew	Divider ratio = integer	—	—	+/- 200	ps
t_W	Output Clock Pulse Width	At 90% or 10%[3]	1	—	—	ns
t_{LOCK}[2]	PLL Lock-in Time		—	—	150	us
t_{PA}	Programmable Delay Unit		100	250	400	ps
t_{IPJIT}	Input Clock Period Jitter		—	—	+/- 200	ps
t_{FBKDLY}	External Feedback Delay		—	—	10	ns
t_{HI}	Input Clock High Time	90% to 90%	0.5	—	—	ns
t_{LO}	Input Clock Low Time	10% to 10%	0.5	—	—	ns
t_{RST}	RST Pulse Width		10	—	—	ns

1. Jitter sample is taken over 10,000 samples of the primary PLL output with clean reference clock.
2. Output clock is valid after t_{LOCK} for PLL reset and dynamic delay adjustment.
3. Using LVDS output buffers.
4. As compared to CLKOP output.

Timing v.F0.11

LatticeXP "C" Sleep Mode Timing

Parameter	Descriptions		Min.	Typ.	Max.	Units
t_{PWRDN}	SLEEPN Low to I/O Tristate		—	20	32	ns
t_{PWRUP}	SLEEPN High to Power Up	LFXP3	—	1.4	2.1	ms
		LFXP6	—	1.7	2.4	ms
		LFXP10	—	1.1	1.8	ms
		LFXP15	—	1.4	2.1	ms
		LFXP20	—	1.7	2.4	ms
$t_{WSLEEPN}$	SLEEPN Pulse Width to Initiate Sleep Mode		400	—	—	ns
t_{WAWAKE}	SLEEPN Pulse Rejection		—	—	120	ns



LFXP3 Logic Signal Connections: 100 TQFP (Cont.)

Pin Number	Pin Function	Bank	Differential	Dual Function
44	GNDIO4	4	-	-
45	PB15A	4	T	PCLKT4_0
46	PB15B	4	C	PCLKC4_0
47	VCCIO4	4	-	-
48	PB19A	4	T	DQS
49	PB19B	4	C	VREF1_4
50	PB24A	4	-	VREF2_4
51	PR18B	3	C[3]	-
52	GNDIO3	3	-	-
53	PR18A	3	T[3]	-
54	PR15B	3	-	VREF1_3
55	PR14A	3	-	VREF2_3
56	PR13B	3	C	-
57	PR13A	3	T	-
58	VCCIO3	3	-	-
59	GNDP1	-	-	-
60	VCCP1	-	-	-
61	PR9B	2	C	PCLKC2_0
62	PR9A	2	T	PCLKT2_0
63	PR8B	2	C	RUM0_PLLC_IN_A
64	PR8A	2	T	RUM0_PLLT_IN_A
65	VCCIO2	2	-	-
66	PR6B	2	-	VREF1_2
67	PR5A	2	-	VREF2_2
68	GNDIO2	2	-	-
69	PR3B	2	C	RUM0_PLLC_FB_A
70	PR3A	2	T	RUM0_PLLT_FB_A
71	VCCAUX	-	-	-
72	TDO	-	-	-
73	VCCJ	-	-	-
74	TDI	-	-	-
75	TMS	-	-	-
76	TCK	-	-	-
77	VCC	-	-	-
78	PT24A	1	-	-
79	PT23A	1	-	D0
80	PT22B	1	-	D1
81	PT21A	1	-	D2
82	VCCIO1	1	-	-
83	PT20B	1	-	D3
84	GNDIO1	1	-	-
85	PT17A	1	-	D4
86	PT16A	1	-	D5
87	PT15B	1	-	D6

LFXP3 Logic Signal Connections: 100 TQFP (Cont.)

Pin Number	Pin Function	Bank	Differential	Dual Function
88	PT14B	1	-	D7
89	PT13B	0	C	BUSY
90	GNDIO0	0	-	-
91	PT13A	0	T	CS1N
92	PT12B	0	C	PCLKC0_0
93	PT12A	0	T	PCLKT0_0
94	VCCIO0	0	-	-
95	PT9A	0	-	DOUT
96	PT8A	0	-	WRITEN
97	PT6A	0	-	DI
98	PT5A	0	-	CSN
99	GND	-	-	-
100	CFG0	0	-	-

1. Applies to LFXP “C” only.
2. Applies to LFXP “E” only.
3. Supports dedicated LVDS outputs.

LFXP3 & LFXP6 Logic Signal Connections: 144 TQFP (Cont.)

Pin Number	LFXP3				LFXP6			
	Pin Function	Bank	Differential	Dual Function	Pin Function	Bank	Differential	Dual Function
139	PT6A	0	-	DI	PT9A	0	-	DI
140	PT5A	0	-	CSN	PT8A	0	-	CSN
141	PT3B	0	-	VREF2_0	PT6B	0	-	VREF2_0
142	CFG0	0	-	-	CFG0	0	-	-
143	CFG1	0	-	-	CFG1	0	-	-
144	DONE	0	-	-	DONE	0	-	-

1. Applies to LFXP “C” only.
2. Applies to LFXP “E” only.
3. Supports dedicated LVDS outputs.

LFXP3 & LFXP6 Logic Signal Connections: 208 PQFP (Cont.)

Pin Number	LFXP3				LFXP6			
	Pin Function	Bank	Differential	Dual Function	Pin Function	Bank	Differential	Dual Function
47	GNDIO6	6	-	-	GNDIO6	6	-	-
48	PL18B	6	C[3]	-	PL26B	6	C[3]	-
49	GND	-	-	-	GND	-	-	-
50	VCCAUX	-	-	-	VCCAUX	-	-	-
51	SLEEPN[1]/TOE[2]	-	-	-	SLEEPN[1]/TOE[2]	-	-	-
52	INITN	5	-	-	INITN	5	-	-
53	VCC	-	-	-	VCC	-	-	-
54	PB2B	5	-	VREF1_5	PB5B	5	-	VREF1_5
55	PB3A	5	T	-	PB6A	5	T	DQS
56	PB3B	5	C	-	PB6B	5	C	-
57	PB4A	5	T	-	PB7A	5	T	-
58	PB4B	5	C	-	PB7B	5	C	-
59	GNDIO5	5	-	-	GNDIO5	5	-	-
60	PB5A	5	T	-	PB8A	5	T	-
61	PB5B	5	C	VREF2_5	PB8B	5	C	VREF2_5
62	PB6A	5	T	-	PB9A	5	T	-
63	PB6B	5	C	-	PB9B	5	C	-
64	VCCIO5	5	-	-	VCCIO5	5	-	-
65	PB7A	5	T	-	PB10A	5	T	-
66	PB7B	5	C	-	PB10B	5	C	-
67	PB8A	5	T	-	PB11A	5	T	-
68	PB8B	5	C	-	PB11B	5	C	-
69	GNDIO5	5	-	-	GNDIO5	5	-	-
70	PB9A	5	-	-	PB12A	5	-	-
71	PB10B	5	-	-	PB13B	5	-	-
72	PB11A	5	T	DQS	PB14A	5	T	DQS
73	PB11B	5	C	-	PB14B	5	C	-
74	VCCIO5	5	-	-	VCCIO5	5	-	-
75	PB12A	5	T	-	PB15A	5	T	-
76	PB12B	5	C	-	PB15B	5	C	-
77	PB13A	5	T	-	PB16A	5	T	-
78	PB13B	5	C	-	PB16B	5	C	-
79	GND	-	-	-	GND	-	-	-
80	VCC	-	-	-	VCC	-	-	-
81	PB14A	4	T	-	PB17A	4	T	-
82	GNDIO4	4	-	-	GNDIO4	4	-	-
83	PB14B	4	C	-	PB17B	4	C	-
84	PB15A	4	T	PCLKT4_0	PB18A	4	T	PCLKT4_0
85	PB15B	4	C	PCLKC4_0	PB18B	4	C	PCLKC4_0
86	PB16A	4	T	-	PB19A	4	T	-
87	VCCIO4	4	-	-	VCCIO4	4	-	-
88	PB16B	4	C	-	PB19B	4	C	-
89	PB17A	4	-	-	PB20A	4	-	-
90	PB18B	4	-	-	PB21B	4	-	-
91	PB19A	4	T	DQS	PB22A	4	T	DQS
92	GNDIO4	4	-	-	GNDIO4	4	-	-

LFXP6 & LFXP10 Logic Signal Connections: 256 fpBGA

Ball Number	LFXP6				LFXP10			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
C2	PROGRAMN	7	-	-	PROGRAMN	7	-	-
C1	CCLK	7	-	-	CCLK	7	-	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-
D2	PL3A	7	T	LUM0_PLLT_FB_A	PL3A	7	T	LUM0_PLLT_FB_A
D3	PL3B	7	C	LUM0_PLLC_FB_A	PL3B	7	C	LUM0_PLLC_FB_A
D1	PL2A	7	T[3]	-	PL5A	7	-	-
E2	PL5A	7	-	VREF1_7	PL6B	7	-	VREF1_7
-	GNDIO7	7	-	-	GNDIO7	7	-	-
E1	PL7A	7	T[3]	DQS	PL7A	7	T[3]	DQS
F1	PL7B	7	C[3]	-	PL7B	7	C[3]	-
E3	PL12A	7	T	-	PL8A	7	T	-
F4	PL12B	7	C	-	PL8B	7	C	-
F3	PL4A	7	T[3]	-	PL9A	7	T[3]	-
F2	PL4B	7	C[3]	-	PL9B	7	C[3]	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-
G1	PL2B	7	C[3]	-	PL11B	7	-	-
G3	PL8A	7	T	LUM0_PLLT_IN_A	PL12A	7	T	LUM0_PLLT_IN_A
G2	PL8B	7	C	LUM0_PLLC_IN_A	PL12B	7	C	LUM0_PLLC_IN_A
H1	PL9A	7	T[3]	-	PL13A	7	T[3]	-
H2	PL9B	7	C[3]	-	PL13B	7	C[3]	-
G4	PL6B	7	-	VREF2_7	PL14A	7	-	VREF2_7
G5	PL14A	7	-	-	PL15B	7	-	-
-	GNDIO7	7	-	-	GNDIO7	7	-	-
J1	PL11A	7	T[3]	-	PL16A	7	T[3]	DQS
J2	PL11B	7	C[3]	-	PL16B	7	C[3]	-
H3	PL13A	7	T[3]	-	PL18A	7	T[3]	-
J3	PL13B	7	C[3]	-	PL18B	7	C[3]	-
H4	VCCP0	-	-	-	VCCP0	-	-	-
H5	GNDP0	-	-	-	GNDP0	-	-	-
K1	PL17A	6	T	PCLKT6_0	PL20A	6	T	PCLKT6_0
K2	PL17B	6	C	PCLKC6_0	PL20B	6	C	PCLKC6_0
-	GNDIO6	6	-	-	GNDIO6	6	-	-
J4	PL15B	6	-	-	PL22A	6	-	-
J5	PL22A	6	-	VREF1_6	PL23B	6	-	VREF1_6
L1	PL16A	6	T[3]	-	PL24A	6	T[3]	DQS
L2	PL16B	6	C[3]	-	PL24B	6	C[3]	-
M1	PL18A	6	T[3]	-	PL25A	6	T	LLM0_PLLT_IN_A
M2	PL18B	6	C[3]	-	PL25B	6	C	LLM0_PLLC_IN_A
K3	PL19A	6	T[3]	-	PL26A	6	T[3]	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
L3	PL19B	6	C[3]	-	PL26B	6	C[3]	-
L4	PL21A	6	T[3]	-	PL28A	6	-	-

LFXP6 & LFXP10 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFXP6				LFXP10			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
K10	GND	-	-	-	GND	-	-	-
K7	GND	-	-	-	GND	-	-	-
K8	GND	-	-	-	GND	-	-	-
K9	GND	-	-	-	GND	-	-	-
L11	GND	-	-	-	GND	-	-	-
L6	GND	-	-	-	GND	-	-	-
T1	GND	-	-	-	GND	-	-	-
T16	GND	-	-	-	GND	-	-	-
D13	VCC	-	-	-	VCC	-	-	-
D4	VCC	-	-	-	VCC	-	-	-
E12	VCC	-	-	-	VCC	-	-	-
E5	VCC	-	-	-	VCC	-	-	-
M12	VCC	-	-	-	VCC	-	-	-
M5	VCC	-	-	-	VCC	-	-	-
N13	VCC	-	-	-	VCC	-	-	-
N4	VCC	-	-	-	VCC	-	-	-
E13	VCCAUX	-	-	-	VCCAUX	-	-	-
E4	VCCAUX	-	-	-	VCCAUX	-	-	-
M13	VCCAUX	-	-	-	VCCAUX	-	-	-
M4	VCCAUX	-	-	-	VCCAUX	-	-	-
F7	VCCIO0	0	-	-	VCCIO0	0	-	-
F8	VCCIO0	0	-	-	VCCIO0	0	-	-
F10	VCCIO1	1	-	-	VCCIO1	1	-	-
F9	VCCIO1	1	-	-	VCCIO1	1	-	-
G11	VCCIO2	2	-	-	VCCIO2	2	-	-
H11	VCCIO2	2	-	-	VCCIO2	2	-	-
J11	VCCIO3	3	-	-	VCCIO3	3	-	-
K11	VCCIO3	3	-	-	VCCIO3	3	-	-
L10	VCCIO4	4	-	-	VCCIO4	4	-	-
L9	VCCIO4	4	-	-	VCCIO4	4	-	-
L7	VCCIO5	5	-	-	VCCIO5	5	-	-
L8	VCCIO5	5	-	-	VCCIO5	5	-	-
J6	VCCIO6	6	-	-	VCCIO6	6	-	-
K6	VCCIO6	6	-	-	VCCIO6	6	-	-
G6	VCCIO7	7	-	-	VCCIO7	7	-	-
H6	VCCIO7	7	-	-	VCCIO7	7	-	-

1. Applies to LFXP “C” only.
2. Applies to LFXP “E” only.
3. Supports dedicated LVDS outputs.

LFXP10, LFXP15 & LFXP20 Logic Signal Connections: 388 fpBGA (Cont.)

Ball Number	LFXP10				LFXP15				LFXP20			
	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function
C20	PT38A	1	T	-	PT43A	1	T	-	PT47A	1	T	-
C21	PT37B	1	C	-	PT42B	1	C	-	PT46B	1	C	-
C22	PT37A	1	T	-	PT42A	1	T	-	PT46A	1	T	-
B22	PT36B	1	C	-	PT41B	1	C	-	PT45B	1	C	-
A21	PT36A	1	T	-	PT41A	1	T	-	PT45A	1	T	-
D15	PT35B	1	C	-	PT40B	1	C	-	PT44B	1	C	-
D14	PT35A	1	T	-	PT40A	1	T	-	PT44A	1	T	-
B21	PT34B	1	C	VREF1_1	PT39B	1	C	VREF1_1	PT43B	1	C	VREF1_1
-	GNDIO1	1	-	-	GNDIO1	1	-	-	GNDIO1	1	-	-
A20	PT34A	1	T	DQS	PT39A	1	T	DQS	PT43A	1	T	DQS
B20	PT33B	1	-	-	PT38B	1	-	-	PT42B	1	-	-
A19	PT32A	1	-	-	PT37A	1	-	-	PT41A	1	-	-
B19	PT31B	1	C	-	PT36B	1	C	-	PT40B	1	C	-
A18	PT31A	1	T	-	PT36A	1	T	-	PT40A	1	T	-
C14	PT30B	1	C	-	PT35B	1	C	-	PT39B	1	C	-
C13	PT30A	1	T	D0	PT35A	1	T	D0	PT39A	1	T	D0
B18	PT29B	1	C	D1	PT34B	1	C	D1	PT38B	1	C	D1
A17	PT29A	1	T	VREF2_1	PT34A	1	T	VREF2_1	PT38A	1	T	VREF2_1
B17	PT28B	1	C	-	PT33B	1	C	-	PT37B	1	C	-
A16	PT28A	1	T	D2	PT33A	1	T	D2	PT37A	1	T	D2
-	GNDIO1	1	-	-	GNDIO1	1	-	-	GNDIO1	1	-	-
B16	PT27B	1	C	D3	PT32B	1	C	D3	PT36B	1	C	D3
A15	PT27A	1	T	-	PT32A	1	T	-	PT36A	1	T	-
B15	PT26B	1	C	-	PT31B	1	C	-	PT35B	1	C	-
A14	PT26A	1	T	DQS	PT31A	1	T	DQS	PT35A	1	T	DQS
D13	PT25B	1	-	-	PT30B	1	-	-	PT34B	1	-	-
D12	PT24A	1	-	D4	PT29A	1	-	D4	PT33A	1	-	D4
B14	PT23B	1	C	-	PT28B	1	C	-	PT32B	1	C	-
A13	PT23A	1	T	D5	PT28A	1	T	D5	PT32A	1	T	D5
-	GNDIO1	1	-	-	GNDIO1	1	-	-	GNDIO1	1	-	-
B13	PT22B	1	C	D6	PT27B	1	C	D6	PT31B	1	C	D6
A12	PT22A	1	T	-	PT27A	1	T	-	PT31A	1	T	-
B12	PT21B	1	C	D7	PT26B	1	C	D7	PT30B	1	C	D7
C12	PT21A	1	T	-	PT26A	1	T	-	PT30A	1	T	-
C11	PT20B	0	C	BUSY	PT25B	0	C	BUSY	PT29B	0	C	BUSY
-	GNDIO0	0	-	-	GNDIO0	0	-	-	GNDIO0	0	-	-
B11	PT20A	0	T	CS1N	PT25A	0	T	CS1N	PT29A	0	T	CS1N
A11	PT19B	0	C	PCLKC0_0	PT24B	0	C	PCLKC0_0	PT28B	0	C	PCLKC0_0
A10	PT19A	0	T	PCLKT0_0	PT24A	0	T	PCLKT0_0	PT28A	0	T	PCLKT0_0
B10	PT18B	0	C	-	PT23B	0	C	-	PT27B	0	C	-
B9	PT18A	0	T	DQS	PT23A	0	T	DQS	PT27A	0	T	DQS
D11	PT17B	0	-	-	PT22B	0	-	-	PT26B	0	-	-
D10	PT16A	0	-	DOUT	PT21A	0	-	DOUT	PT25A	0	-	DOUT
A9	PT15B	0	C	-	PT20B	0	C	-	PT24B	0	C	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-	GNDIO0	0	-	-
C8	PT15A	0	T	WRITEN	PT20A	0	T	WRITEN	PT24A	0	T	WRITEN
B8	PT14B	0	C	-	PT19B	0	C	-	PT23B	0	C	-
A8	PT14A	0	T	VREF1_0	PT19A	0	T	VREF1_0	PT23A	0	T	VREF1_0
C7	PT13B	0	C	-	PT18B	0	C	-	PT22B	0	C	-

LFXP10, LFXP15 & LFXP20 Logic Signal Connections: 388 fpBGA (Cont.)

Ball Number	LFXP10				LFXP15				LFXP20			
	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function
G7	VCCAUX	-	-	-	VCCAUX	-	-	-	VCCAUX	-	-	-
T16	VCCAUX	-	-	-	VCCAUX	-	-	-	VCCAUX	-	-	-
T7	VCCAUX	-	-	-	VCCAUX	-	-	-	VCCAUX	-	-	-
G10	VCCIO0	0	-	-	VCCIO0	0	-	-	VCCIO0	0	-	-
G11	VCCIO0	0	-	-	VCCIO0	0	-	-	VCCIO0	0	-	-
G8	VCCIO0	0	-	-	VCCIO0	0	-	-	VCCIO0	0	-	-
G9	VCCIO0	0	-	-	VCCIO0	0	-	-	VCCIO0	0	-	-
H8	VCCIO0	0	-	-	VCCIO0	0	-	-	VCCIO0	0	-	-
G12	VCCIO1	1	-	-	VCCIO1	1	-	-	VCCIO1	1	-	-
G13	VCCIO1	1	-	-	VCCIO1	1	-	-	VCCIO1	1	-	-
G14	VCCIO1	1	-	-	VCCIO1	1	-	-	VCCIO1	1	-	-
G15	VCCIO1	1	-	-	VCCIO1	1	-	-	VCCIO1	1	-	-
H15	VCCIO1	1	-	-	VCCIO1	1	-	-	VCCIO1	1	-	-
H16	VCCIO2	2	-	-	VCCIO2	2	-	-	VCCIO2	2	-	-
J16	VCCIO2	2	-	-	VCCIO2	2	-	-	VCCIO2	2	-	-
K16	VCCIO2	2	-	-	VCCIO2	2	-	-	VCCIO2	2	-	-
L16	VCCIO2	2	-	-	VCCIO2	2	-	-	VCCIO2	2	-	-
M16	VCCIO3	3	-	-	VCCIO3	3	-	-	VCCIO3	3	-	-
N16	VCCIO3	3	-	-	VCCIO3	3	-	-	VCCIO3	3	-	-
P16	VCCIO3	3	-	-	VCCIO3	3	-	-	VCCIO3	3	-	-
R16	VCCIO3	3	-	-	VCCIO3	3	-	-	VCCIO3	3	-	-
R15	VCCIO4	4	-	-	VCCIO4	4	-	-	VCCIO4	4	-	-
T12	VCCIO4	4	-	-	VCCIO4	4	-	-	VCCIO4	4	-	-
T13	VCCIO4	4	-	-	VCCIO4	4	-	-	VCCIO4	4	-	-
T14	VCCIO4	4	-	-	VCCIO4	4	-	-	VCCIO4	4	-	-
T15	VCCIO4	4	-	-	VCCIO4	4	-	-	VCCIO4	4	-	-
R8	VCCIO5	5	-	-	VCCIO5	5	-	-	VCCIO5	5	-	-
T10	VCCIO5	5	-	-	VCCIO5	5	-	-	VCCIO5	5	-	-
T11	VCCIO5	5	-	-	VCCIO5	5	-	-	VCCIO5	5	-	-
T8	VCCIO5	5	-	-	VCCIO5	5	-	-	VCCIO5	5	-	-
T9	VCCIO5	5	-	-	VCCIO5	5	-	-	VCCIO5	5	-	-
M7	VCCIO6	6	-	-	VCCIO6	6	-	-	VCCIO6	6	-	-
N7	VCCIO6	6	-	-	VCCIO6	6	-	-	VCCIO6	6	-	-
P7	VCCIO6	6	-	-	VCCIO6	6	-	-	VCCIO6	6	-	-
R7	VCCIO6	6	-	-	VCCIO6	6	-	-	VCCIO6	6	-	-
H7	VCCIO7	7	-	-	VCCIO7	7	-	-	VCCIO7	7	-	-
J7	VCCIO7	7	-	-	VCCIO7	7	-	-	VCCIO7	7	-	-
K7	VCCIO7	7	-	-	VCCIO7	7	-	-	VCCIO7	7	-	-
L7	VCCIO7	7	-	-	VCCIO7	7	-	-	VCCIO7	7	-	-

1. Applies to LFXP “C” only.
2. Applies to LFXP “E” only.
3. Supports dedicated LVDS outputs.

Thermal Management

Thermal management is recommended as part of any sound FPGA design methodology. To assess the thermal characteristics of a system, Lattice specifies a maximum allowable junction temperature in all device data sheets. Designers must complete a thermal analysis of their specific design to ensure that the device and package do not exceed the junction temperature limits. Refer to the Thermal Management document to find the device/package specific thermal values.

For Further Information

For further information regarding Thermal Management, refer to the following located on the Lattice website at www.latticesemi.com.

- Thermal Management document
- Technical Note TN1052 - Power Estimation and Management for LatticeECP/EC and LatticeXP Devices
- Power Calculator tool included with Lattice's ispLEVER design tool, or as a standalone download from www.latticesemi.com/software

Commercial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP15E-3FN484C	300	1.2V	-3	fpBGA	484	COM	15.5K
LFXP15E-4FN484C	300	1.2V	-4	fpBGA	484	COM	15.5K
LFXP15E-5FN484C	300	1.2V	-5	fpBGA	484	COM	15.5K
LFXP15E-3FN388C	268	1.2V	-3	fpBGA	388	COM	15.5K
LFXP15E-4FN388C	268	1.2V	-4	fpBGA	388	COM	15.5K
LFXP15E-5FN388C	268	1.2V	-5	fpBGA	388	COM	15.5K
LFXP15E-3FN256C	188	1.2V	-3	fpBGA	256	COM	15.5K
LFXP15E-4FN256C	188	1.2V	-4	fpBGA	256	COM	15.5K
LFXP15E-5FN256C	188	1.2V	-5	fpBGA	256	COM	15.5K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20E-3FN484C	340	1.2V	-3	fpBGA	484	COM	19.7K
LFXP20E-4FN484C	340	1.2V	-4	fpBGA	484	COM	19.7K
LFXP20E-5FN484C	340	1.2V	-5	fpBGA	484	COM	19.7K
LFXP20E-3FN388C	268	1.2V	-3	fpBGA	388	COM	19.7K
LFXP20E-4FN388C	268	1.2V	-4	fpBGA	388	COM	19.7K
LFXP20E-5FN388C	268	1.2V	-5	fpBGA	388	COM	19.7K
LFXP20E-3FN256C	188	1.2V	-3	fpBGA	256	COM	19.7K
LFXP20E-4FN256C	188	1.2V	-4	fpBGA	256	COM	19.7K
LFXP20E-5FN256C	188	1.2V	-5	fpBGA	256	COM	19.7K

Industrial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP3C-3QN208I	136	1.8/2.5/3.3V	-3	PQFP	208	IND	3.1K
LFXP3C-4QN208I	136	1.8/2.5/3.3V	-4	PQFP	208	IND	3.1K
LFXP3C-3TN144I	100	1.8/2.5/3.3V	-3	TQFP	144	IND	3.1K
LFXP3C-4TN144I	100	1.8/2.5/3.3V	-4	TQFP	144	IND	3.1K
LFXP3C-3TN100I	62	1.8/2.5/3.3V	-3	TQFP	100	IND	3.1K
LFXP3C-4TN100I	62	1.8/2.5/3.3V	-4	TQFP	100	IND	3.1K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP6C-3FN256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	5.8K
LFXP6C-4FN256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	5.8K
LFXP6C-3QN208I	142	1.8/2.5/3.3V	-3	PQFP	208	IND	5.8K
LFXP6C-4QN208I	142	1.8/2.5/3.3V	-4	PQFP	208	IND	5.8K
LFXP6C-3TN144I	100	1.8/2.5/3.3V	-3	TQFP	144	IND	5.8K
LFXP6C-4TN144I	100	1.8/2.5/3.3V	-4	TQFP	144	IND	5.8K